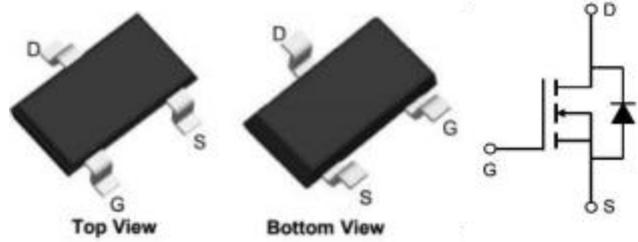


N-Channel Enhancement Mode

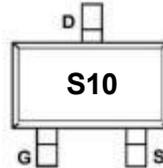
Features

- Advanced Trench Process Technology
- Low Threshold Voltage
- Fast Switching Speed
- Halogen-Free & Lead-Free



Application

- Load Switch for Portable Devices
- Voltage controlled small signal switch



SOT-23
Marking: S10

Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	3	A
Peak Drain Current, Pulsed ¹⁾	I_{DM}	10	A
Power Dissipation ²⁾	P_{tot}	1.25	W
Operating Junction	T_J	-55~150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55~150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	100	$^\circ\text{C/W}$

Note:

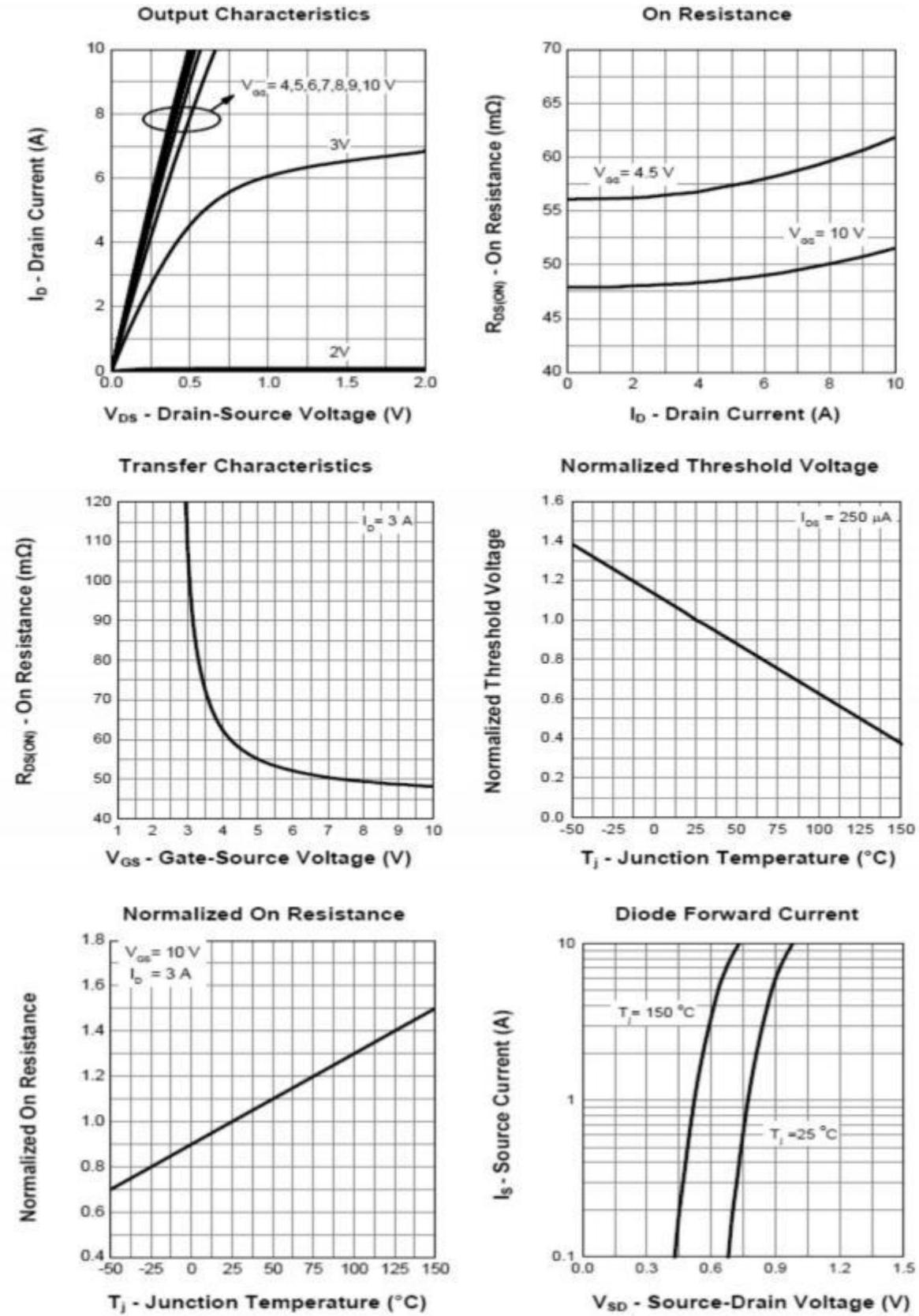
1) Pulse width $\leq 100\mu\text{s}$, duty cycle $\leq 1\%$, limited by T_{jmax} .

2) Device mounted on FR-4 substrate PC board, 2ozcopper, with 1-inch square copper plate in still air.

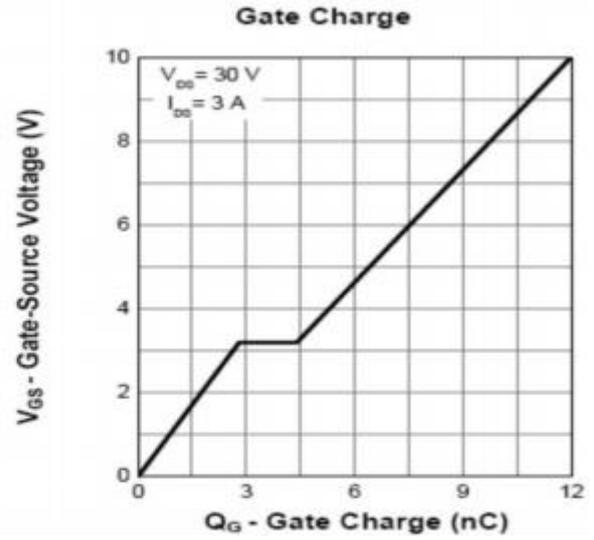
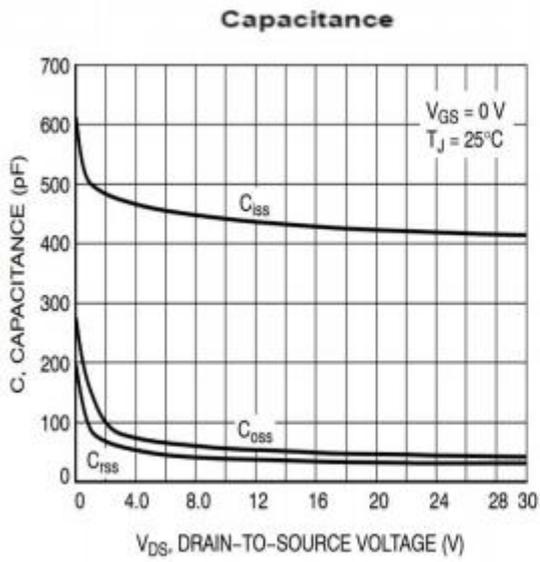
Characteristics at T_a = 25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at V _{GS} =0V, I _D =250μA	BV _{DSS}	60			V
Drain-Source Leakage Current at V _{DS} =60V, V _{GS} =0V	I _{DSS}			1	uA
Gate Leakage Current at V _{DS} =0V, V _{GS} = ±20	I _{GSS}			±100	nA
Gate-Source Threshold Voltage at V _{DS} = V _{GS} , I _D = 250 μA	V _{GS(th)}	1		2.2	V
Drain-Source On-State Resistance at V _{GS} = 10 V, I _D = 3A at V _{GS} =4.5V, I _D =3A	R _{DS(on)}		75 90	90 110	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at V _{DS} =5V, I _D =3A	g _{fs}		6		S
Input Capacitance at V _{DS} =30V, V _{GS} =0V, f=1MHz	C _{iss}		410		pF
Output Capacitance at V _{DS} =30V, V _{GS} =0V, f=1MHz	C _{oss}		35		pF
Reverse Transfer Capacitance at V _{DS} =30V, V _{GS} =0V, f=1MHz	C _{rss}		32		pF
Gate charge total at V _{DS} = 30 V, I _D = 3 A, V _{GS} = 10 V at V _{DS} = 30 V, I _D = 3 A, V _{GS} = 4.5 V	Q _g		12 5.9		nC
Gate to Source Charge at V _{GS} =10V, V _{DS} =30V, I _D =3A	Q _{gs}		2.8		nC
Gate to Drain Charge at V _{GS} =10V, V _{DS} =30V, I _D =3A	Q _{gd}		1.6		nC
Turn-On Delay Time at V _{DS} =30V, I _D = 3A, V _{GS} =10V, R _G =4.5Ω	t _{d(on)}		10		nS
Turn-On Rise Time at V _{DS} =30V, I _D = 3A, V _{GS} =10V, R _G =4.5Ω	t _r		23		nS
Turn-Off Delay Time at V _{DS} =30V, I _D = 3A, V _{GS} =10V, R _G =4.5Ω	t _{d(off)}		34		nS
Turn-Off Delay Time at V _{DS} =30V, I _D = 3A, V _{GS} =10V, R _G =4.5Ω	t _f		4.6		nS
Gate resistance at V _{DS} = 0 V, V _{GS} =0V, f = 1 MHz	R _g		15		Ω
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at I _S =3A, V _{GS} = 0 V	V _{SD}			1	V
Body Diode Reverse Recovery Time at I _S = 3 A, di/dt = 100 A / μs	t _{rr}		34		nS
Body Diode Reverse Recovery Charge at I _S = 3 A, di/dt = 100 A / μs	Q _{rr}		4.6		nC

Electrical Characteristics Curves



Electrical Characteristics Curves



Test Circuits

Fig.1- 1 Switching times test circuit

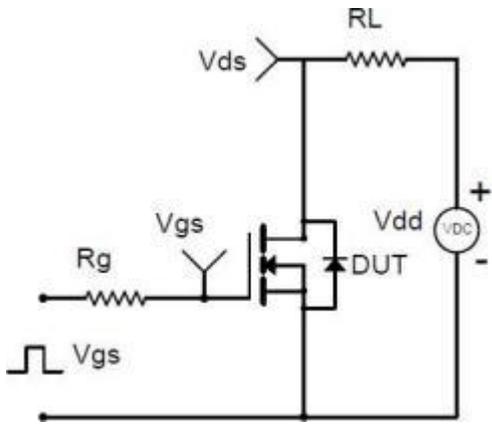


Fig.1-2 Switching Waveform

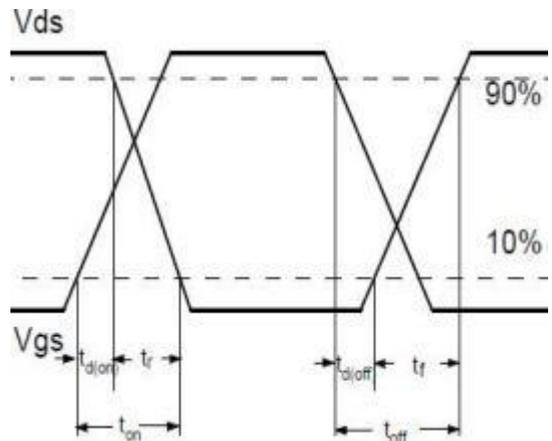


Fig.2- 1 Gate charge test circuit

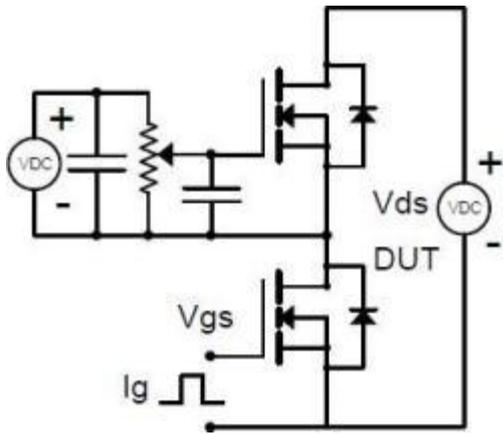


Fig.2-2 Gate charge waveform

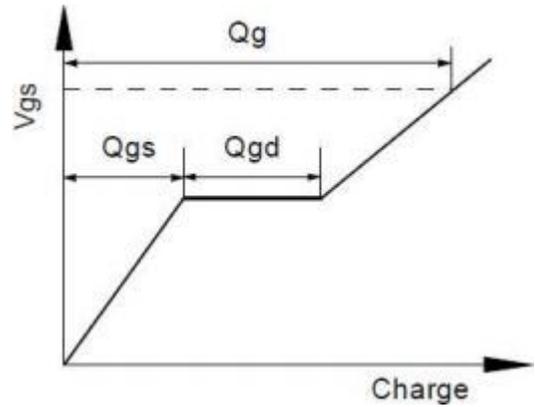


Fig.3- 1 Avalanche test circuit

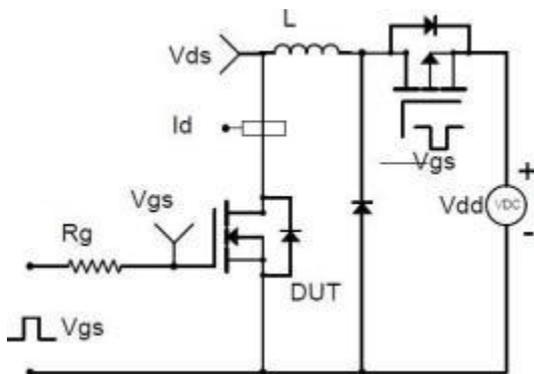
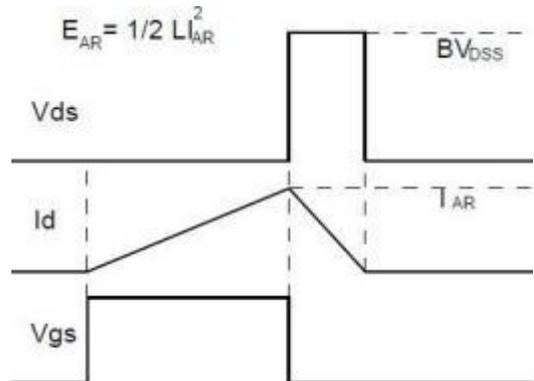
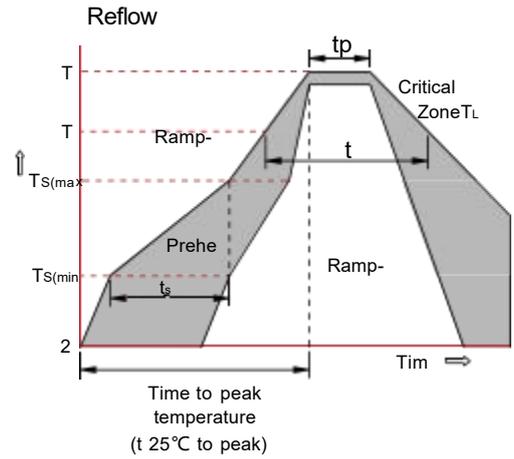
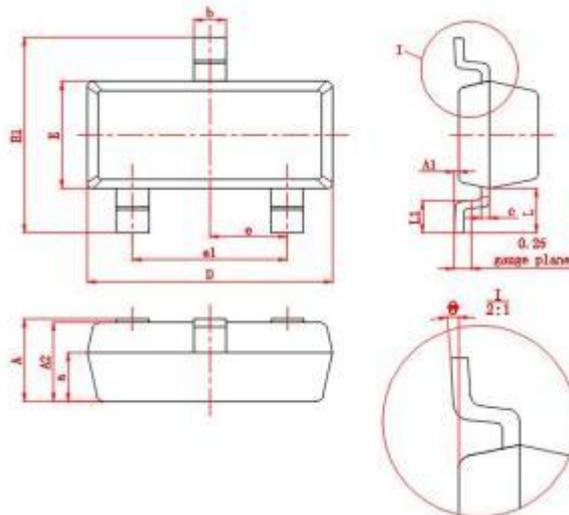


Fig.3-2 Avalanche waveform



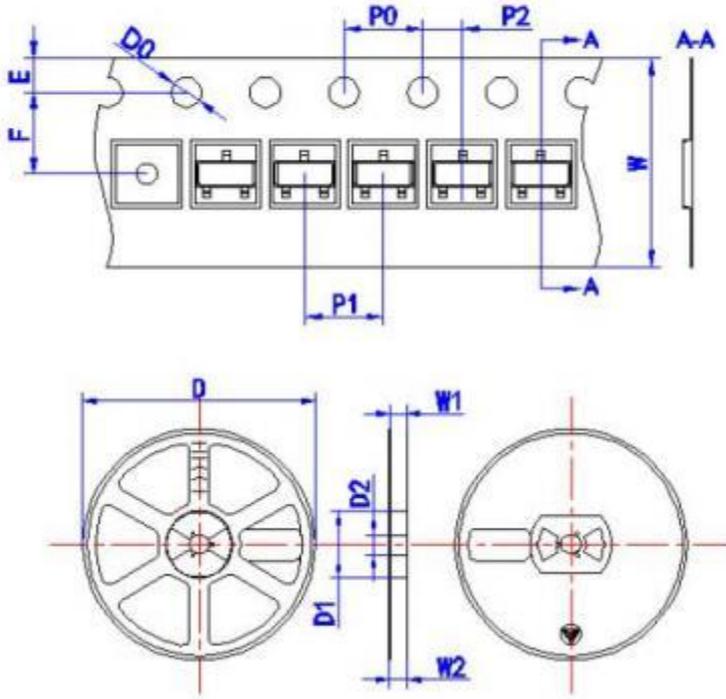
Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C


Package Outline Dimensions (Units: mm)
SOT-23


符号	尺寸		符号	尺寸		符号	尺寸	
	Min	Max		Min	Max		Min	Max
A	0.9	1.15	E	1.2	1.4	c	0.08	0.15
A1	0	0.1	E1	2.25	2.55	L	(0.55)	
A2	0.9	1.05	e	(0.95)		L1	0.3	0.5
a	(0.6)		e1	1.8	2.0	θ	0°	8°
D	2.8	3.0	b	0.3	0.5			

Emboss Carrier Tape&Reel



Symbol	Dimension in Millimeters
Tape	
D0	1.50+0.10/-0.00
E	1.75±0.10
F	3.50±0.10
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
W	8.00+0.3/-0.1
Reel	
D	178.0±2.00
D1	54.40±1.00
D2	13.00±1.00
W1	9.50±1.00
W2	12.30±1.00